11-21-05

PATENT ANL-IN-03-023

## THE UNITED STATES PATENT AND TRADEMARK OFFICE

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**Applicants** 

Ruxandra Baurceanu et al.

Title

LAYERED STRUCTURE OF CU-CONTAINING

SUPERCONDUCTOR AND AG OR AG ALLOYS WITH CU

Serial No.

10/648,052

Filing Date

August 26, 2003

Art Unit

1754

Examiner

Colleen P. Cooke

Docket No.

**ANL 273** 

Date

November 17, 2005

## MAIL STOP NO FEE AMENDMENT

Director of Patents U.S. Patent and Trademark Office P.O. Box 1450 Alexandria, VA 22313-1450

## **RESPONSE AFTER FINAL**

This Response replies to the FINAL Office Action dated September 16, 2005, a response to which is due December 16, 2005.

## REMARKS

Reconsideration of this application is requested.

Submitted herewith is a Declaration of Dr. Balachandran, an inventor in the present case. Dr. Balachandran reviewed the Examiner's calculations of the amount of copper in